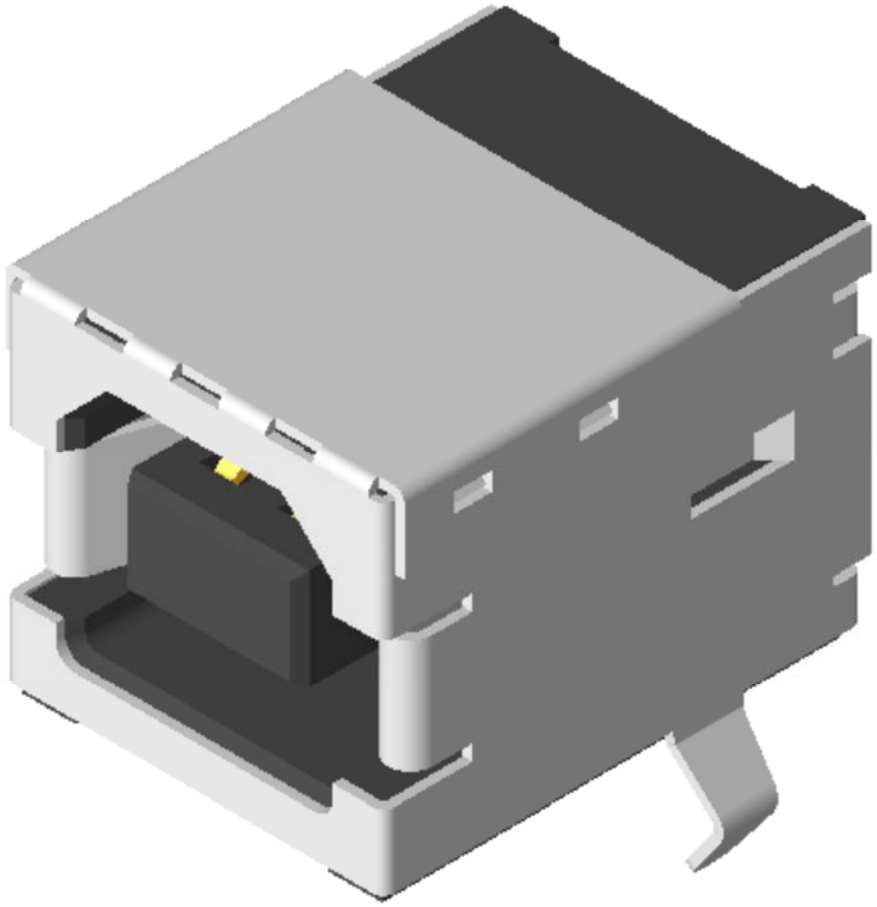
PRODUCT SPECIFICATION



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REVISION:	ECR/ECN INFORMATION:		PRODUCT NO	HTUSRXR-241 SERIES	SHEET No
A	EC No: / DATE:	NEW SPEC. 2015/06/08	PRODUCT NAME	USB B TYPE FLAT 4PIN DIP	1 of 4

DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-UB-0017	Linda	Jerry	kimi

1.0 SCOPE

This Product Specification covers the USB connector series with terminal tin plating and cover selective plating for IR reflow process.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER(S)

USB B TYPE CONNECTOR
P/N:HTUSRXR-241 SERIES

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See the appropriate drawings (HTUSRXR-241 SERIES)for information on dimensions, materials, plating and markings.

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

MIL-STD-1344A
EIA-STD- 202
EIA-364

4.0 RATINGS OF CONNECTOR

1. Rate Voltage: 30 V DC
   Rate Current: 1.5 A DC
2. Operating temperature: -40°C to +110°C
   Storage temperature : -40°C to +85°C

5.0 LECTRICAL REQUIREMENTS

Test Ref	DESCRIPTION	TEST CONDITION	REQUIREMENT
5.1	**Contact Resistance**	Mate connectors: apply a maximum voltage of **20** mV and a current of **100** mA.	**30** milliohms MAXIMUM
5.2	**Insulation Resistance**	Unmated connector, mounted to a PCB: apply a voltage of **500** VDC between adjacent terminals and between terminals to ground.	**1000** Megohms MINIMUM
5.3	**Dielectric Withstanding Voltage**	**500** VAC rms (**1**mA cutoff current) for **60** seconds duration between adjacent terminals and terminals.	**No Breakdown**
5.4	**Capacitance**	Test between adjacent contacts to 1 Megahertz max per EIA-364.	**2** picofarad MAXIMUM
5.5	**Current Temperature Rating**	Mate connector and measure the temperature rise at the rated current **(1.5Amps)**.	**30**℃ rise MAXIMUM from initial

6.0 MECHANICAL REQUIREMENTS

Test Ref	DESCRIPTION	TEST CONDITION	REQUIREMENT
6.1	**Connector Mate and Unmate Force**	Mate connector at a rate of **25 ± 6** mm (**1 ± ¼** inch) per minute.	**3.57Kgf (35** N) MAXIMUM mate force **1.5 Kgf (15** N) MINMUM unmate force
6.2	**Terminal Retention**	Apply a pull out force in the axial direction of the contact per Mil-STD-1344A method 2007.1	**0.8** Kgf minimum
6.3	**Vibration**	Mated connector and subject to the following vibration condition, for a period of 15 minutes in each 3 mutually perpendicular axes. Per EIA-364-28,Test condition V,Test letter A.	Contact Resistance **30** milliohms MAXIMUM Discontinuity ≦ **1**usec
6.4	**Mechanical Shock**	Subject mated connector to 30 G half sine in 11 msec according to EIA-364-27.	Contact Resistance **30** milliohms MAXIMUM Discontinuity ≦ **1**usec
6.5	**Durability**	Mate this connector with it's mating part of 1500 cycles. Other conditions follow per EIA-364-09.	Contact Resistance **30** milliohms MAXIMUM

7.0 ENVIRONMENTAL REQUIREMENTS

Test Ref	DESCRIPTION	TEST CONDITION	REQUIREMENT
7.1	**Steady State Humidity**	Mate connectors; Temperature: **40±2**℃ Relative humidity: **90-95**% Duration time: **168** hours	Contact Resistance **30** milliohms MAXIMUM
7.2	**Solderability**	Dip solder tails into the molten solder (held at **245 ± 5**℃) up to 1.0mm from the bottom of the housing for **3 ± 0.5** seconds	Solderable area shall have minimum of **95%** solder coverage
7.3	**Temperature Life (Thermal Aging)**	Subject mated connector to ambient temperature 125°C for 250 hours. Per Mil-STD-1344A method 1005.1 condition B	Contact Resistance **30** milliohms MAXIMUM
7.4	**Thermal Shock**	Subject mated connector to 10 cycles of exposure at -40°C to +110°C per EIA-364-32.	Contact Resistance **30** milliohms MAXIMUM
7.5	**Reflow**	Place connector in IR reflow , Peak temperature:**260 ± 5**°C for **5±1** seconds	Appearance : No damage

8.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage.
See appropriate sales drawings.

9.0 RECOMMENDED REFLOW PROFILE

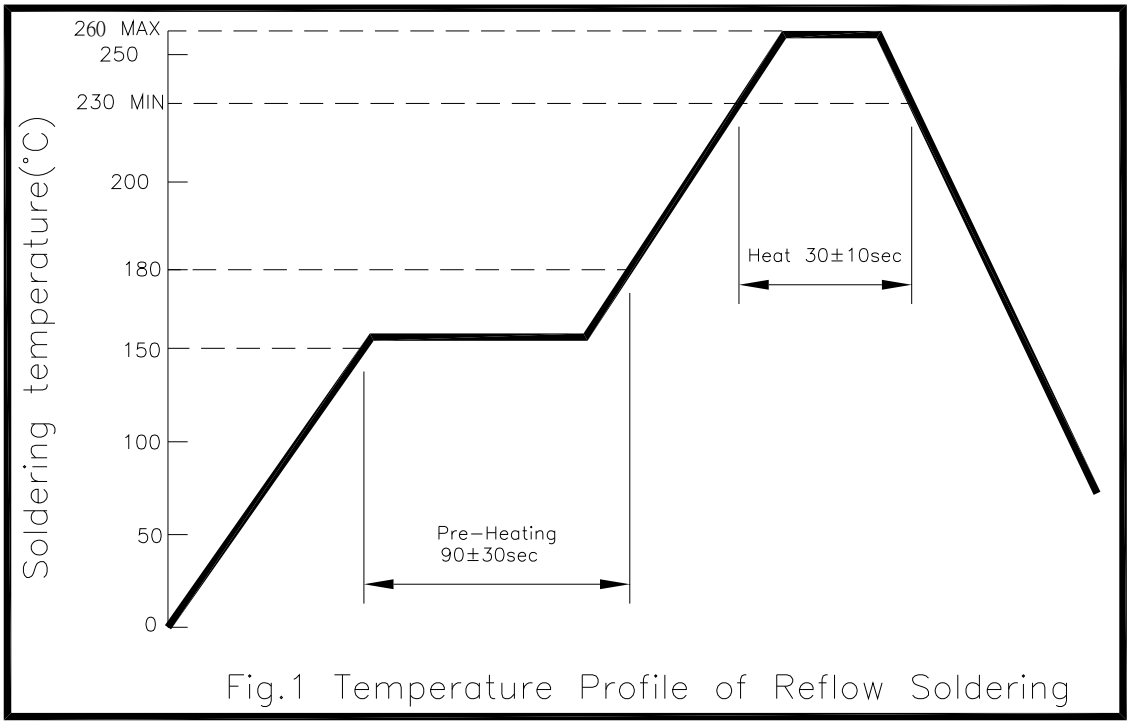

Fig.1 Temperature Profile of Reflow Soldering

A

AcRon 文件制訂、修訂、廢止申請單

RD-PS-A-001-223

文件編號	PS-UB-0017	文件名稱	HTUSRXR-24 Series 規格書		
申請部門	業務部	申請人	Frances	日 期	6/8/15
制訂單位	工程部	制訂人	Linda	日 期	

☑ 制訂 ☐ 修訂 ☐ 廢止原因說明

新制訂

相關單位審查

6/9/15

Jeff 6/8/15

Judy 6/9/15

核准

08/08/15